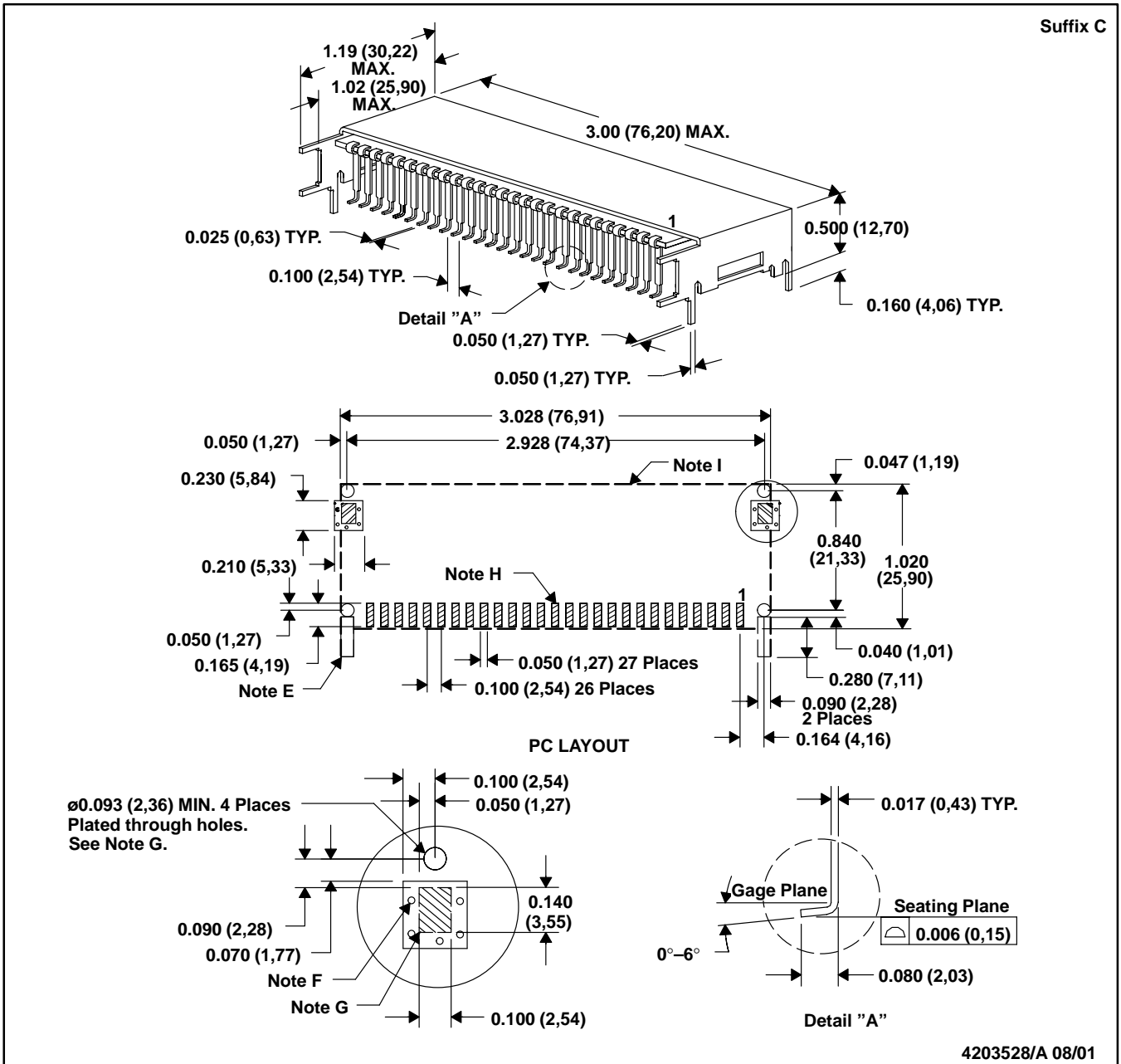


ENG (R-MSIP-G27)

METAL SINGLE-IN-LINE MODULE



- NOTES:
- All linear dimensions are in inches (mm).
  - This drawing is subject to change without notice.
  - 2 place decimals are  $\pm 0.030$  ( $\pm 0,76$ mm).
  - 3 place decimals are  $\pm 0.010$  ( $\pm 0,25$ mm).
  - Recommended mechanical keep out area.
  - Vias are recommended to improve copper adhesion.
  - Solder mask openings to copper island for solder joints to mechanical pins. Electrically connect case to power ground plane.
  - Power pin connections should utilize two or more vias per input, ground and output pin.
  - Case outline reference.

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